

Serial No. 09/395,179
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Reply to the Office Action dated April 24, 2005
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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

R 1.126
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Claims 1-38 (canceled).

Claim 29 (previously presented): A lid material for a lid which is to be fuse-bonded to a peripheral upper surface of a case having an open top and a housing space for an electronic component, the lid material comprising:

a core layer;

a nickel-based metal layer composed of a nickel-based metal mainly comprising nickel, an entire thickness of the nickel-based metal layer being press- and diffusion-bonded onto the core layer; and

a brazing material layer press-bonded onto the nickel-based metal layer such that the total thickness of the core layer, the nickel-based metal layer, and the brazing material layer is reduced by a ratio of between about 30% to about 60%;

wherein the nickel-based metal layer has a maximum-to-minimum thickness ratio T1/T2 of 1.4 to 15.

Claim 30 (previously presented): A lid material as set forth in claim 29, wherein the core layer is composed of an iron-nickel-based alloy mainly comprising iron and nickel.

Claim 31 (previously presented): A lid material as set forth in claim 29, wherein the brazing material layer is composed of a soft brazing material having a melting point